142. (Amended) A power distribution arrangement according to claim 138 wherein said interconnect means also includes a plurality of control lines for connection t selected others of said voltage supply points on said printhead.

E3

143. (Amended) A power distribution arrangement according to claim 138 wherein said interconnect means is in the form of one or more printed circuit boards which connect directly to said busbars, with wire bonds connecting the printed circuit boards to said printhead.

E4

147. (Amended) A power distribution arrangement according to claim 142 wherein the printhead is in the form of a printhead chip manufactured by a MEMS processing technique.

150. (Amended) A power distribution arrangement according to claim 149, said ink supply unit including: a slot for insertion of said printhead; and a series of elongated chambers for the storage of separate color inks, said chambers being interconnected with said slot for the supply of ink to said printhead; wherein:

E5

said busbars are disposed along said ink supply unit; and

the interconnect means take the form of a tape automated bonding strip similarly disposed along the outside of said ink supply unit having a series of control lines along one surface thereof for mating with corresponding external series of control lines, said tape automated bonding strip further having a repeating series of interconnects to said printhead, said interconnects interconnecting said control lines and said busbars to said printhead.

Please cancel claim 146.